

Special Issue

Structural Health Monitoring: Latest Applications and Data Analysis

Message from the Guest Editors

Dear Colleagues, This Special Issue is devoted to Structural Health Monitoring (SHM), more precisely to its most recent applications and obtained data analysis. Monitoring the state of engineering structures is unquestionably a timely topic, but it is also a very broad and interdisciplinary one. Both novel sensor systems and measurement, data collecting, and processing techniques are of relevance in this context. SHM techniques encompass all commonly used technical diagnostics and non-destructive testing methods, including electromagnetic, high-frequency, thermovision, radiography, ultrasound, and others. Each of the aforementioned methods presents unique issues, not just in terms of measurement methodology, but data processing as well. As a result, the processing of signals or images for the needs of qualitative and quantitative assessment of the structures under examination is also particularly intriguing in this context. We invite scientists working in the broad field of technical diagnostics and nondestructive testing to submit original work on any of the above-mentioned themes.

Guest Editors

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Deadline for manuscript submissions

closed (30 April 2023)



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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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